





Dispensing cell DC-CNC 1150

The big-time compact dispensing cell for secure sealing, bonding, and potting

Compact, flexible, high-performance

By combining mixing and dispensing technology with maintenance-free CNC linear axes, the DC-CNC 1150 meets even the most complex requirements, including three-dimensional material application of sealants, glues or encapsulants.

It has integrated material preparation and can be equipped with either piston or gear pumps. State-of-the-art control technology from Siemens or Beckhoff ensures optimum interaction between the metering process and motion sequences and also controls complex automation systems. The modular control design allows extensive integration into your production system.



Compact design

- High-speed gantry trolley
- Integrated control cabinet
- Complete enclosure



High flexibility

- All RAMPF mixing and dispensing systems can be used
- Processing of up to four components with up to two mixing systems
- Flexible automation solutions from manual to robotic loading



Highly productive

- Increased productivity through optional dual mixing systems
- High travel speeds during dispensing



Accurate metering

- Highly precise metering close to the mixing system
- Servo-driven gear pumps for up to four components
- Short hoses between metering pumps and mixing headfor highest accuracy

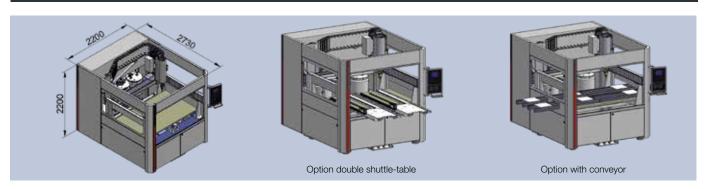


Controls

- Beckhoff or Siemens
- Quick and flexible programming of different parts through recipe management
- Integrated process controls
- Intuitives Bedienkonzept über RAMPF-HMI

DC-CNC 1150

Equipment and expansion options



Technical Data

Flow rate, mixing ratio, viscosity depends on selected mixing system

Max. travel speed	$X, Y = 60 \text{ m min}^{-1}$
Repeatability	< 0.10 mm (ISO 9283)
NC controls	Beckhoff or Siemens
Electrical supply	400 V/16 – 32 A / 50 Hz (60 Hz)
Power consumption	5.5 – 12 kW
Compressed air supply	> 5 bar at max. flow 800 I min ⁻¹ , depending on application
Compressed air consumption	5–20 l min-1
Weight	approx. 2800 kg
Work area	X, Y, Z = max. 1150, 1000, 300 mm

Options (more upon request)

- HP rinse recycling system or HP water rinsing system
- Nucleation controller for air load controls of gasket materials
- Material recirculation system and temperature controller
- Automatic thin-film degassing for bubble-free potting
- Various automation equipment available (rotary index tables, shuttle tables, conveyor lines, customized automation)
- Individual process monitoring and visualization
- Process data collection, interfacing to customers' PPS
- Integration of up to four material components
- Integrated shot-weight scale, nozzle check station, nozzle cleaning station